

Ordering Information

Type	Case Style	Thread	Electrical configuration	Voltage (dc)	Capacitance in picofarads (pF)	Capacitance Tolerance	Dielectric	Hardware
SF	B	C	P	500	0102	M	X	0
Syfer Filter	4.75mm Hex Head	8-32 UNC	C = C Filter L = L-C Filter P = Pi Filter	050 = 50V 100 = 100V 200 = 200V 500 = 500V	First digit is 0. Second and third digits are significant figures of capacitance code. The fourth digit is the number of zeros following. Examples: 0101 = 100pF 0332 = 3300pF	M = $\pm 20\%$ Z = -20+80%	C = COG/NPO X = X7R	0 = Without 1 = With

Note: The addition of a 4-digit numerical suffix code can be used to denote changes to the standard part.

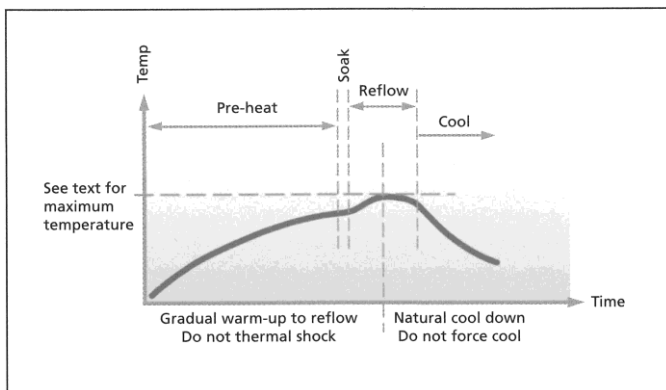
Options include for example: change of pin length / custom body dimensions or threads / alternative voltage rating / non-standard intermediate capacitance values / test requirements.

Please refer specific requests to the factory.

Surface Mount and Panel Mount Solder-in filters

Solder pad layouts are included with the detailed information **for each part**.

Recommended soldering profile



Soldering of filters

The soldering process should be controlled such that the filter does not experience any thermal shocks which may induce thermal cracks in the ceramic dielectric.

The pre-heat temperature rise of the filter should be kept to around 2°C per second. In practice successful temperature rises tend to be in the region of 1.5°C to 4°C per second dependent upon substrate and components.

The introduction of a soak after pre-heat can be useful as it allows temperature uniformity to be established across the substrate thus preventing substrate warping. The magnitude or direction of any warping may change on cooling imposing damaging stresses upon the filter.

E01, E03, E07 SBSP ranges are compatible with all standard solder types including lead-free, maximum temperature 260°C. For SBSG, SBSM and SFSS ranges, solder time should be minimised, and the temperature controlled to a maximum of 220°C. For SFSR, SFST and SFSU ranges the maximum temperature is 250°C.

Cooling to ambient temperature should be allowed to occur naturally. Natural cooling allows a gradual relaxation of thermal mismatch stresses in the solder joints. Draughts should be avoided. Forced air cooling can induce thermal breakage, and cleaning with cold fluids immediately after a soldering process may result in cracked filters.

Note: The use of FlexiCap™ terminations is strongly recommended to reduce the risk of mechanical cracking.

Soldering to axial wire leads

Soldering temperature

The tip temperature of the iron should not exceed 300°C.

Dwell time

Dwell time should be 3-5 seconds maximum to minimise the risk of cracking the capacitor due to thermal shock.

Heat sink

Where possible, a heat sink should be used between the solder joint and the body, especially if longer dwell times are required.

Bending or cropping of wire leads

Bending or cropping of the filter terminations should not be carried out within 4mm (0.157") of the epoxy encapsulation, the wire should be supported when cropping.

Soldering irons should not be used for mounting surface mount filters as they can result in thermal shock damage to the chip capacitor.

A more comprehensive application note covering installation of all Syfer products is available on the Syfer website.